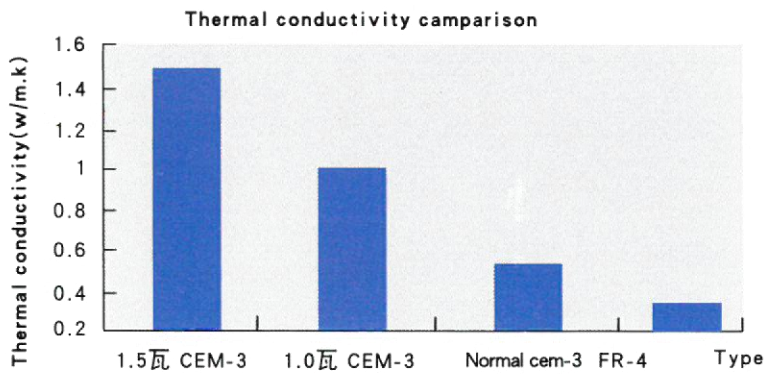


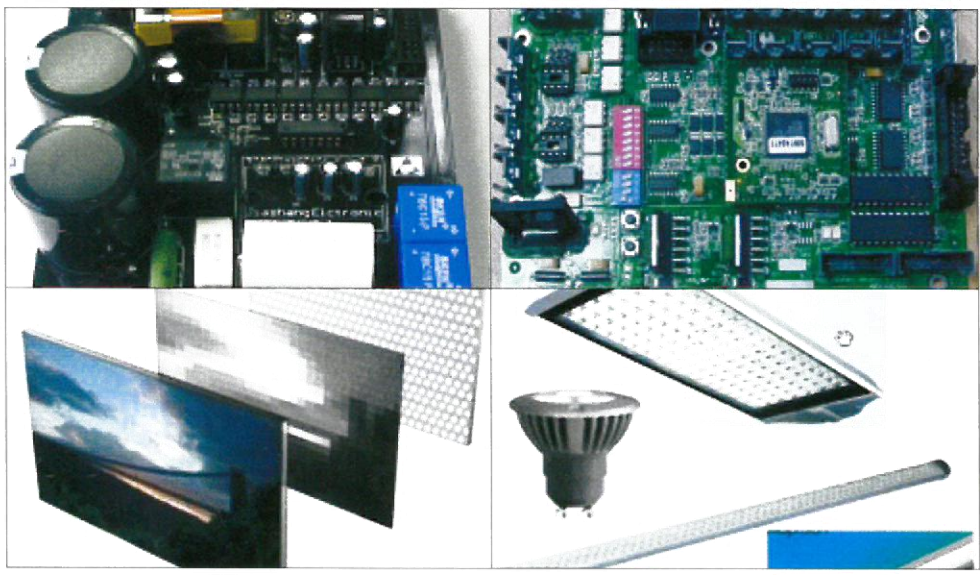
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# Thermal conductivity

## 导热CEM-3和其他材料热导率比较 Thermal Conductivity comparison



## 主要应用 Applications



## 产品系列/ Purchasing information

厚度 Thickness	铜箔 Copper foil	标准尺寸 Standard size
0.8-3.2mm	18um-105um	37"×49"、41"×49"、43"×49"

※ Any specific inquiry could be available upon request

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## Thermal conductivity

### 特性/ Features

- 良好的导热性能，热导率  $\geq 1.0W/m.K$
- Excellent thermal conductivity,  $\geq 1.0W/m.K$
- 优异的耐热性能，适应无铅制程
- Excellent solder heat endurance, Lead-free compatible laminate
- 基材白色，不透明，遮光性好
- White and opaque with good color-change resistance
- 优秀的机械加工性
- Excellent mechanical processability

### 应用领域/ Applications

- LED背光源、户外照明、汽车电子等（见下图）
- LED backlight module、oudoor Lighting、Automotive electronics (refer to figure)

### 主要特性 / General properties

检测项目 Item	单位 Unit	检测条件 Test Condition	规范值 Spec	类型1 Type1	类型2 Type2
热导率 Thermal Conductivity	W/ m.K	ASTM D5470 Hot Plate	$\geq 1.0$	1.02	1.51
玻璃化转变温度Tg	°C	DSC	$\geq 110$	120	120
剥离强度 1oz Peel Strength	N/mm	288°C, 10S	$\geq 1.05$	1.56	1.53
热应力 Thermal stress	S	288°C, solder dip	$> 10$	60s No delamination	60s No delamination
弯曲强度 Flexural Strength	N/mm <sup>2</sup>	经向LW	$\geq 276$	326	326
		纬向CW	$\geq 186$	235	235
燃烧性Flammability	—	E 24/125	UL94V-0	V-0	V-0
表面电阻 Surface Resistivity	MΩ	After moisture	$\geq 1.0 \times 10^4$	$4.62 \times 10^6$	$4.62 \times 10^6$
体积电阻 Volume Resistivity	MΩ.cm	After moisture	$\geq 1.0 \times 10^6$	$3.76 \times 10^8$	$3.76 \times 10^8$
介电常数 Dielectric Constant	—	1MHZ C 24/23/50	—	5.1	5.6
介质损耗角正切 Loss Tangent	—	1MHZ C 24/23/50	$\leq 0.035$	0.019	0.019
耐电弧Arc Resistance	S	D48/50+D0.5/23	$\geq 60$	128	128
击穿电压 Dielectric Breakdown	KV	IPC-TM-650 2.5.2.6 D48/50+D0.5/23	$\geq 40$	60	60
吸水率 Moisture Absorption	%	D24/23	$\leq 0.5$	0.35	0.35
CTI	V	IEC-60112	$\geq 600$	600	600

Specimen Thickness : 1.6mm ;

Explanation: C: Humidity conditioning;

D: Immersion conditioning in distilled water ;

E: Temperature conditioning ;